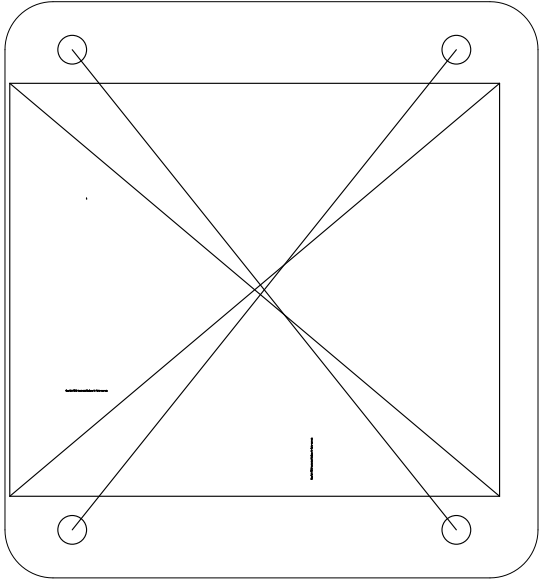


Dotted box > PCB manufacturer info

Layer Name	Type	Material	Thickness (mils)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mils	Not specified	1	0
F.Paste	Top Solder Paste		0 mils		1	0
F.Mask	Top Solder Mask	Not specified	0.3937 mils	Not specified	3.3	0
F.Cu	copper		1.37795 mils		1	0
Dielectric	core	FR4	59.44882 mils	Not specified	4.5	0.02
B.Cu	copper		1.37795 mils		1	0
B.Mask	Bottom Solder Mask	Not specified	0.3937 mils	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mils		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mils	Not specified	1	0

BOARD CHARACTERISTICS

Copper Layer Count:	2	Board Thickness:	1.6000 mm
Board overall dimensions:	70.4850 mm x 76.2000 mm		
Min track/spacing:	0.0000 mm / 0.0000 mm	Min hole diameter:	0.3000 mm
Copper Finish:	None	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		
Outer Copper Weight	1 oz		
Via Covering	Tented		

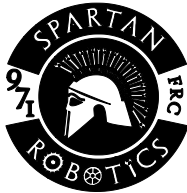


NOTES

- 1.Layers: 2
- 2.Thickness: 1.6
- 3.Surface finish: HASL
- 4.Outer Copper Weight: 2oz
- 5.Via covering: Tented
- 6.Min hole size: .3mm
- 7.Gold Fingers: No
- 8.Castellated Holes: No
- 9.Edge Plating: No

LAYERS

User.1
Edge.Cuts



Spartan Robotics

Sheet:		
File: PowerDistribution.kicad_pcb		
Title: Power Distribution Board		
Size: A4	Date: 2023-10-29	Rev: R1
KiCad E.D.A. 8.0.2-1		Page: 1/1